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Appl. No. 10/510,588; Docket No. NL02 1100US
Amdt. dated December 20, 2006
Response to Office Action dated October 2, 2006

REMARKS/ARGUMENTS

Claims 4-9 are pending in the application.

Claim 5 has been cancelled. Claims 4, 6, 7, 8, and 9 have been amended. New claims 13-17 have been added. Applicant believes no fees are due for these additional claims. However, if fees are required, please charge to the Deposit Account listed below.

The amendment to claim 4 incorporates the features of claim 5, "*the first patterned metal layer further includes parts projecting with respect to the intermediate layer,*" Furthermore, the carrier of the electronic device has two metal layers that can be patterned independently of one another in that there is "*a first patterned metal layer*" and "*a second patterned metal layer.*" Additionally, the feature of "the electronic device that *includes a first and a second electric element,*" allows for interconnection of two or more chips within a package. That "*the electric elements are interconnected by an interconnect track that is defined in the first metal layer, while a corresponding interconnect track is absent in the second metal layer,*" further shows that the two metal layers can be independently patterned. These amendments are supported by the Specification and contain no new matter.

Claims 4-9 are rejected under 35 U.S.C. §102(e) as being clearly anticipated by *Coffman*, US Patent 6,451,627 (Figures 12 & 13)

Claim 9 is rejected under 35 U.S.C. §103(a) as being unpatentable over *Coffman* as applied to Claim 4.

Claims 4, 5, 7, and 8 are rejected under 35 U.S.C. 102(e) as being clearly anticipated by *Ohsawa et al.* US Patent 6,351,025 (Figure 1A-E).

Claim 9 is rejected under 35 U.S.C. §103(a) as being unpatentable over *Ohsawa* as applied to Claim 4.

Rejections under Coffman

In reviewing reference, Applicants note that *Coffman* does not disclose the feature of the carrier of the electronic device has two metal layers that can be patterned independently of one another in that there is "*a first patterned metal layer*" and "*a second patterned metal layer.*" Thus, independent claim 4 is not anticipated and the dependent claims 6-9, likewise, are not anticipated, as well.

With respect to claim 9, *Coffman* does not suggest or teach Applicant's claimed features, as amended. In that claim 9 is dependent upon allowable claim 8, claim 9 is also allowable.

Rejections under Ohsawa

Applicants have reviewed *Ohsawa* and respectfully asserts, that in Fig. 1 is appears the masks 25a, 25b are composed of photoresist and are removed again, unlike Applicants' invention.

Ohsawa's packaging is clearly different than the package presented in the invention. Essentially, a standard leadframe is made, with inner leads 28 and outer leads 27. See Fig. 2&3. The embodiments shown in Fig. 4 are different again: here is the frame attached to a further carrier 43, and a chip 41 is positioned in a cavity 44 inside the carrier 43.

Unlike Applicant's claimed feature of "the electronic device that *includes a first and a second electric element*," allows for interconnection of two or more chips within a package, *Ohsawa* does not disclose that one of the layers is an interconnect between two chips within the package.

Thus, independent claim 4 is not anticipated by *Ohsawa* and the dependent claims 4, 7, 8 likewise, are not anticipated, as well.

New Claims 13-17

For these new claims, Applicant asserts that these claims are not anticipated by or suggested or taught by the cited references. The arguments presented *supra*, are applicable.

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Conclusion

Applicants believe they have addressed all of the Examiner's concerns. The claims, as presented, are allowable. A timely Notice of Allowance is earnestly requested.

Please charge any fees other than the issue fee and credit any overpayments to Deposit Account 50-4019.

Respectfully submitted,

Date: 20- DEC-2006

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